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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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# FFPF30UP20DN

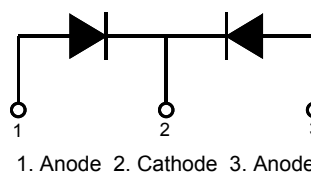
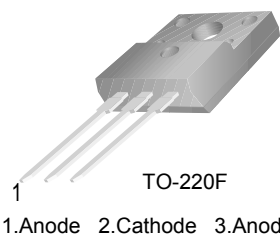
## Ultrafast Recovery Power Rectifier

### Features

- Ultrafast with Soft Recovery : < 45ns (@ $I_F = 15A$ )
- High Reverse Voltage :  $V_{RRM} = 200V$
- Avalanche Energy Rated
- Planar Construction

### Applications

- Output Rectifiers
- Switching Mode Power Supply
- Free-wheeling diode for motor application
- Power switching circuits



### Absolute Maximum Ratings (per diode) $T_C = 25^\circ C$ unless otherwise noted

Symbol	Parameter	Value	Units
$V_{RRM}$	Peak Repetitive Reverse Voltage	200	V
$V_{RWM}$	Working Peak Reverse Voltage	200	V
$V_R$	DC Blocking Voltage	200	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_C = 105^\circ C$	15	A
$I_{FSM}$	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	150	A
$T_J, T_{STG}$	Operating Junction and Storage Temperature	- 65 to +150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	3.8	$^\circ C/W$

### Package Marking and Ordering Information

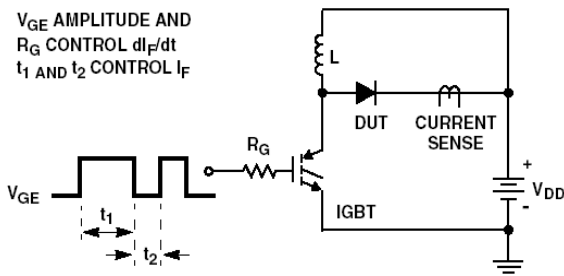
Device Marking	Device	Package	Reel Size	Tape Width	Quantity
F30UP20DN	FFPF30UP20DNTU	TO-220F	-	-	50

### Electrical Characteristics (per diode) $T_C = 25^\circ\text{C}$ unless otherwise noted

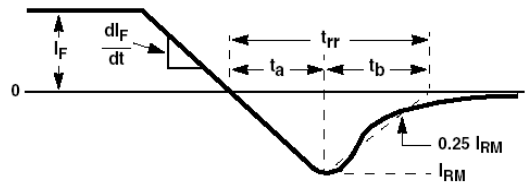
Symbol	Parameter	Min.	Typ.	Max.	Units	
$V_{FM}^*$	$I_F = 15\text{A}$ $I_F = 15\text{A}$	$T_C = 25^\circ\text{C}$	-	-	1.15	V
		$T_C = 100^\circ\text{C}$	-	-	1.0	V
$I_{RM}^*$	$V_R = 200\text{V}$ $V_R = 200\text{V}$	$T_C = 25^\circ\text{C}$	-	-	100	$\mu\text{A}$
		$T_C = 100^\circ\text{C}$	-	-	500	$\mu\text{A}$
$t_{rr}$	$I_F = 1\text{A}, di/dt = 100\text{A}/\mu\text{s}, V_{CC} = 30\text{V}$ $I_F = 15\text{A}, di/dt = 200\text{A}/\mu\text{s}, V_{CC} = 130\text{V}$	$T_C = 25^\circ\text{C}$	-	-	35	ns
		$T_C = 25^\circ\text{C}$	-	-	45	ns
$t_a$ $t_b$ $Q_{rr}$	$I_F = 15\text{A}, di/dt = 200\text{A}/\mu\text{s}, V_{CC} = 130\text{V}$	$T_C = 25^\circ\text{C}$	-	13	-	ns
		$T_C = 25^\circ\text{C}$	-	11	-	ns
		$T_C = 25^\circ\text{C}$	-	24	-	nC
$W_{AVL}$	Avalanche Energy ( $L = 40\text{mH}$ )	20	-	-	mJ	

\* Pulse Test: Pulse Width=300 $\mu\text{s}$ , Duty Cycle=2%

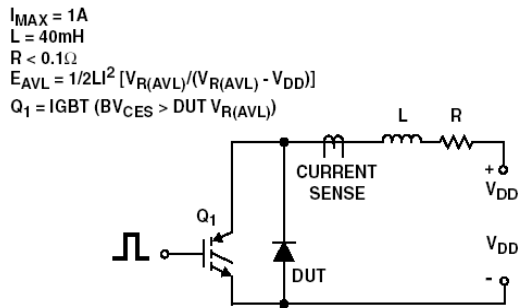
### Test Circuit and Waveforms



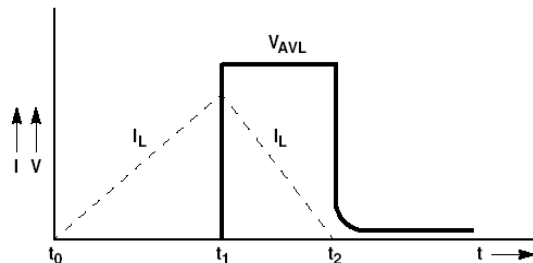
$t_{rr}$  TEST CIRCUIT



$t_{rr}$  WAVEFORMS AND DEFINITIONS



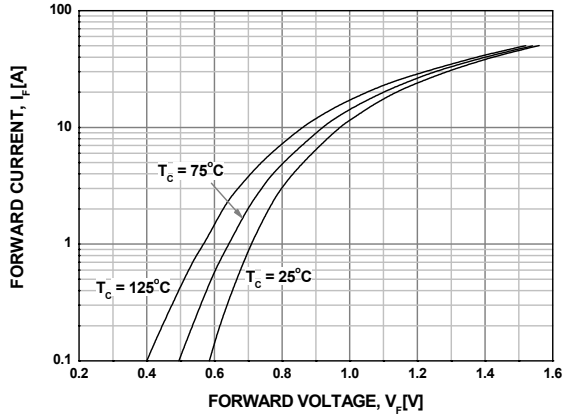
AVALANCHE ENERGY TEST CIRCUIT



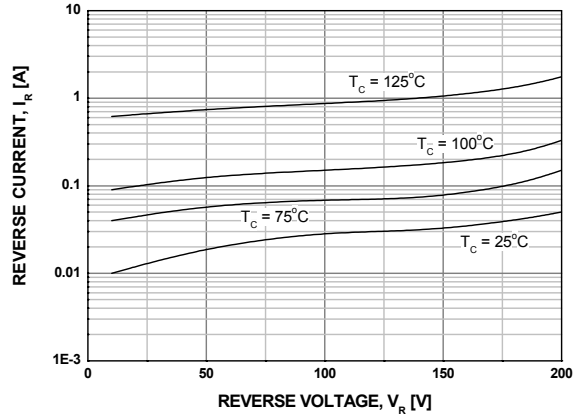
AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

## Typical Performance Characteristics

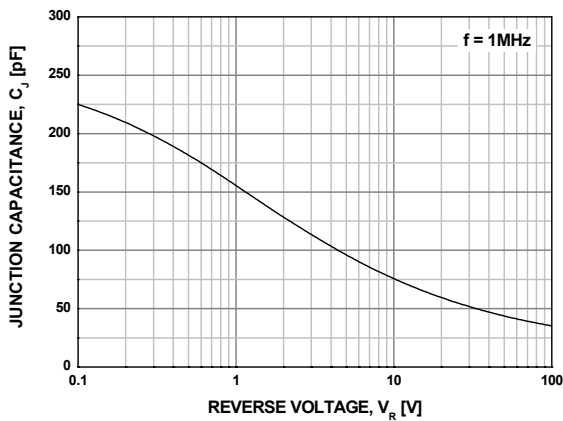
**Figure 1. Typical Forward Voltage Drop**



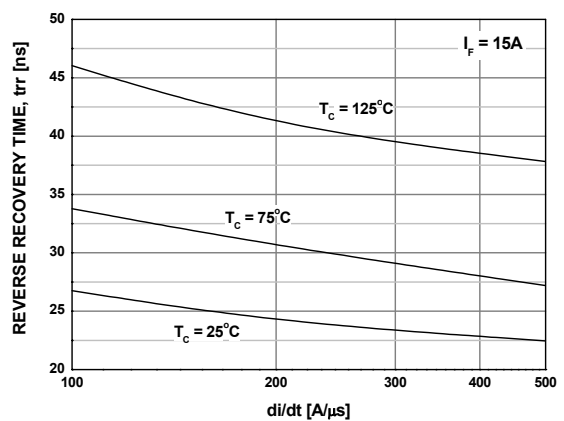
**Figure 2. Typical Reverse Current**



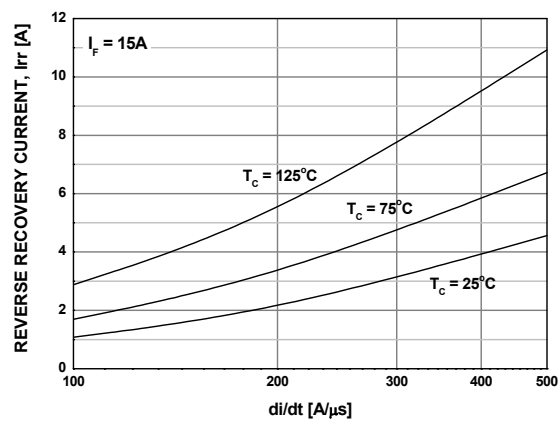
**Figure 3. Typical Junction Capacitance**



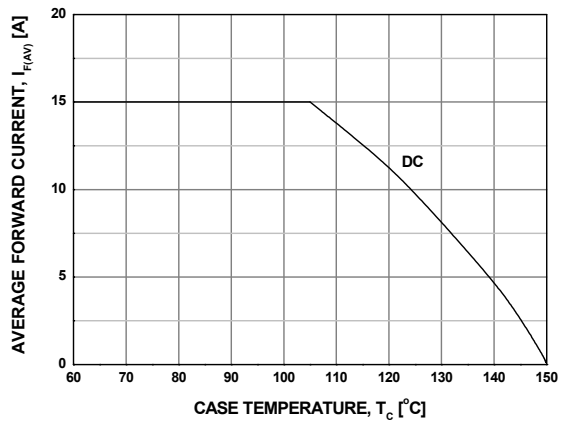
**Figure 4. Typical Reverse Recovery Time**



**Figure 5. Typical Reverse Recovery Current**

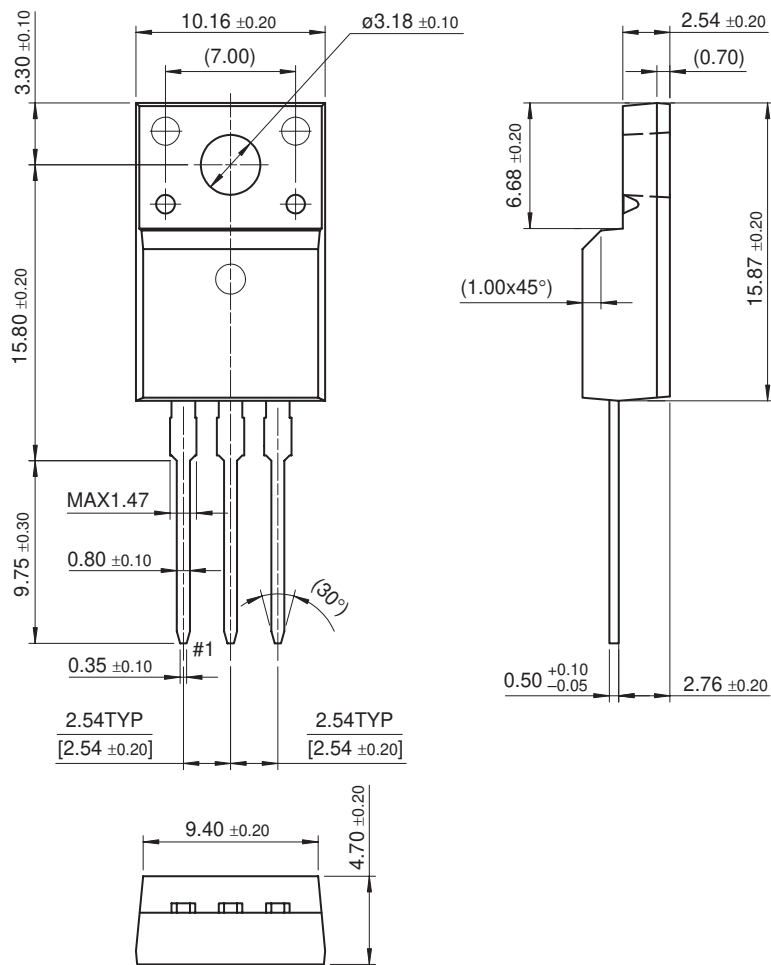


**Figure 6. Forward Current Deration Curve**



# Package Demensions

## TO-220F



Dimensions in Millimeters

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DOME™	HiSeC™	MSX™	RapidConfigure™	TruTranslation™
EcoSPARK™	I <sup>2</sup> C™	MSXPro™	RapidConnect™	UHC™
E <sup>2</sup> CMOS™	i-Lo™	OCX™	μSerDes™	UltraFET®
EnSigna™	ImpliedDisconnect™	OCXPro™	Scalar Pump™	UniFET™
FACT™	IntelliMAX™	OPTOLOGIC®	SILENT SWITCHER®	VCX™
FACT Quiet Series™		OPTOPLANAR™	SMART START™	Wire™
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Programmable Active Droop™		PowerEdge™	SuperSOT™-3	

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